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ASX RELEASE

29 April 2022

FURTHER TECHNICAL UPDATE

4DS Memory Limited (ASX:4DS) (**4DS**) (the **Company**), today provides a further update on technical achievements.

Third Platform Lot manufacture

On 11 April 2022 4DS stated it would provide a further update to investors on the implementation of process improvements for the Third Platform Lot. The Company is pleased to inform shareholders that additional characterisation of the short loop wafers confirmed the decision to release the improved etch process. The Third Platform Lot is scheduled to be processed with this improved etch process by mid-May.

The expected out-of-fab date for the Third Platform Lot, incorporating process improvements, remains July 2022 as previously guided.

ENDS

Authorised for release by the Board.

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About 4DS

4DS Memory Limited (ASX: 4DS), with facilities located in Silicon Valley, is a semiconductor development company of non-volatile memory technology, pioneering Interface Switching ReRAM for next generation gigabyte storage in mobile and cloud. Established in 2007, 4DS owns a patented IP portfolio, comprising 32 USA patents granted (of which 4 have expired) and 1 patent application, which have been developed in-house to create high-density Storage Class Memory. 4DS has a joint development agreement with Western Digital subsidiary HGST, a global storage leader, which accelerates the evolution of 4DS' technology. 4DS also collaborates with imec, a world-leading research and innovation hub in nanoelectronics and digital technologies. The combination of imec's widely acclaimed leadership in microchip technology and profound software and information and communication technology expertise makes them unique.

For more information, please visit www.4dsmemory.com.